ABSTRACT

A substrate clamping apparatus and a substrate clamping method relate to the technical field of semiconductor equipment. The substrate clamping apparatus comprises: a detection module, for acquiring the type data of a substrate; a chuck, for placing the substrate; an execution module, including: a pneumatic unit, provided on the chuck, for clamping the substrate; a main line, one end of the main line being connected to a gas source, and the other end being connected to the pneumatic unit; a pressure regulating unit, provided on the main line, for regulating the gas pressure in the main line; a processing module, for receiving the type data, and controlling the pressure regulating unit to regulate the gas pressure in the main line based on the type data, and allowing the gas pressure to correspond to the type data. The substrate clamping apparatus can automatically output corresponding clamping forces for different substrates, thereby improving the production efficiency of the substrate.